

RClamp3521ZA **RailClamp®** Low Capacitance **ESD and EOS Protection**

PROTECTION PRODUCTS

Description

RailClamp® TVS diodes are designed to provide ESD and EOS protection on high-speed ports. RClamp3521ZA is a 1-line, bidirectional device with a typical capacitance of only 0.45pF and a working voltage of 3.5V. It is manufactured using Semtech's proprietary snap-back technology which minimizes both ESD peak clamping and TLP clamping voltages. The dynamic resistance is extremely low (0.12 Ohms typical) providing optimum protection of sensitive circuits.

RClamp3521ZA is in a 2-pin SLP0603P2X3F package measuring 0.6 x 0.3 x 0.25mm. Leads are finished with lead-free NiAu.

Features

- ESD protection for high speed lines to:
 - IEC 61000-4-2 (ESD): +/-20kV (Contact)
 - IEC 61000-4-4 (EFT): 4kV, 80A
 - IEC 61000-4-5 (Lightning): 6A (tp = 8/20µs)
- Ultra-small package
- Protects one line
- Low ESD clamping voltage
- Working voltage: 3.5V
- Low capacitance: 0.45 pF Typical •
- Low leakage current •
- Low dynamic resistance
- Solid-state silicon-avalanche technology

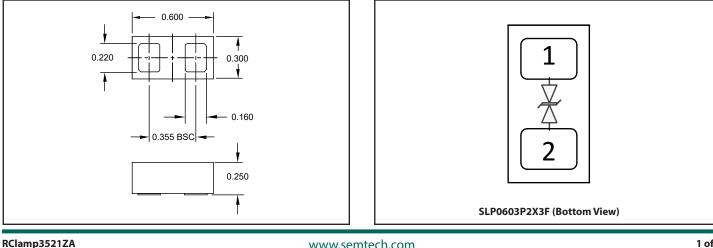
Mechanical Characteristics

- SLP0603P2X3F package
- Pb-Free, Halogen Free, RoHS/WEEE compliant
- Nominal Dimensions: 0.6 x 0.3 x 0.25 mm
- Lead Finish: NiAu
- Marking: Marking code
- Packaging: Tape and Reel

Applications

- USB3.0 / USB 3.1
- USB Type-C
- V-By-One
- MHL/MDDI
- LVDS Interfaces

Schematic & Pin Configuration



Final Datasheet Revision Date

Package Dimension

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Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = $1.2/50\mu s$)	P _{PK}	30	W
Peak Pulse Current (tp = $1.2/50\mu$ s)	I _{PP}	6	А
ESD per IEC 61000-4-2 (Air) ⁽¹⁾ ESD per IEC 61000-4-2 (Contact) ⁽¹⁾	V _{ESD}	±25 ±20	kV
Operating Temperature	T,	-40 to +125	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Electrical Characteristics (T=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Reverse Stand-Off Voltage	V _{RWM}				3.5	V
Reverse Breakdown Voltage	V _{BR}	I _t =1mA	5.5	7.5	8.5	V
Reverse Leakage Current	I _R	V _{RWM} = 3.5V		<1	50	nA
Holding Current	I _H		50	120		mA
Clamping Voltage ²	V _c	$I_{pp} = 6A$, tp = 1.2/50µs, 8/20µs Combination Waveform		5		V
ESD Clamping Voltage ³	V _c	I= 4A, tlp = 0.2/100ns		4.5		- V
		I=16A, tlp = 0.2/100ns		6		
Dynamic Resistance ^{3,4}	R _{DYN}	tlp = 0.2/100ns		0.12		Ω
Junction Capacitance	C	$V_{R} = 0V, f = 1MHz$		0.45	0.55	рF

Notes:

1) ESD gun return path connected to ESD ground plane.

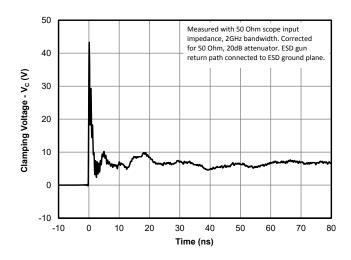
2) Measured using a 1.2/50us voltage, 8/20us current combination waveform, $R_s = 8$ Ohms. Clamping is defined as the peak voltage across the device after the device snaps back to a conducting state.

3) Transmission Line Pulse Test (TLP) Settings: tp = 100ns, tr = 0.2ns, I_{TLP} and V_{TLP} averaging window: t1 = 70ns to t2 = 90ns.

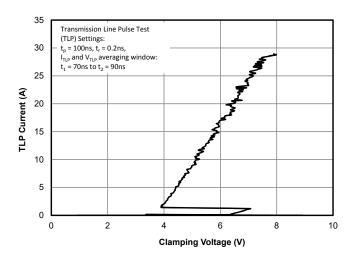
4) Dynamic resistance calculated from $I_{_{TLP}} = 4A$ to $I_{_{TLP}} = 16A$

Typical Characteristics

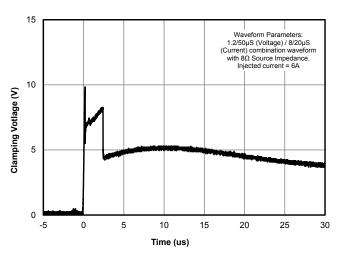
ESD Clamping (8kV Contact per IEC 61000-4-2)



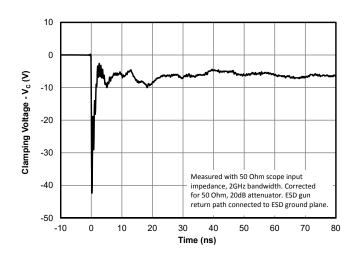
TLP Characteristic (Positive Pulse)



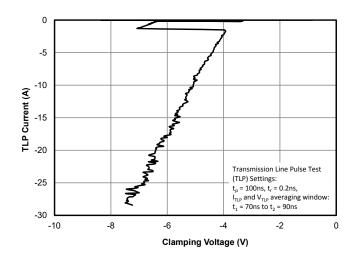
Clamping Characteristic (6A, Combination Waveform)



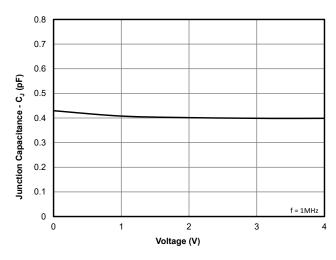
ESD Clamping (-8kV Contact per IEC 61000-4-2)



TLP Characteristic (Negative Pulse)





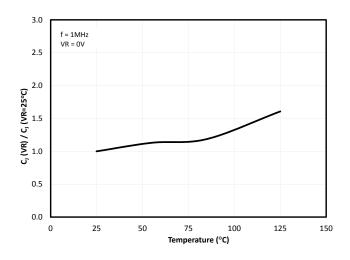


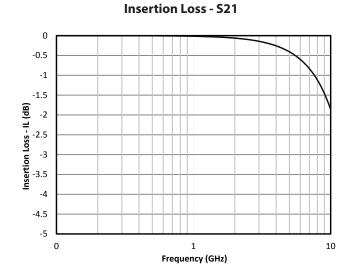
RClamp3521ZA Final Datasheet Revision Date

Rev 2.2 5/16/2019 www.semtech.com

Typical Characteristics (Continued)

Capacitance vs. Temperature





Application Information

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joints. The figure at the right details Semtech's recommended mounting pattern. Recommended assembly guidelines are shown in Table 1. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing parameters will require some experimentation to get the desired solder application.

Solder Stencil

Stencil design is one of the key factors which will determine the volume of solder paste which is deposited onto the land pad. The area ratio of the stencil aperture will determine how well the stencil will print. The area ratio takes into account the aperture shape, aperture size, and stencil thickness. A minimum area ratio of 0.66 is preferred for the subject package. The area ratio of a rectangular aperture is given as:

Area Ratio = (L * W) / (2 * (L + W) * T)

Where:

L = Aperture Length W = Aperture Width T = Stencil Thickness

Semtech recommends a stencil with square aperture and rounded corners for consistent solder release. The stencil should be laser cut with electro-polished finish. A stencil thickness of 0.075mm (0.003") is recommended. A 0.100mm (0.004") stencil may be used, however the stencil opening may need to be increased slightly to achieve the desired area ratio to ensure proper solder coverage on the pad.

Recommended Mounting Pattern

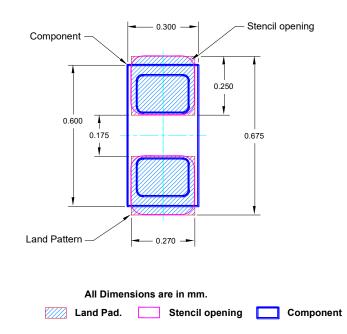
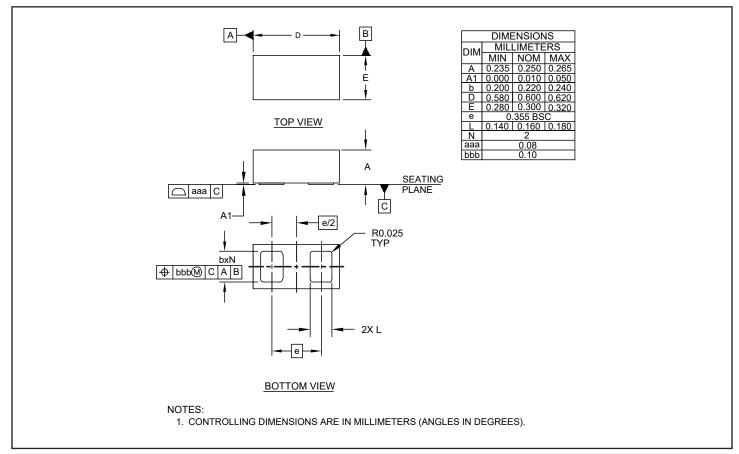


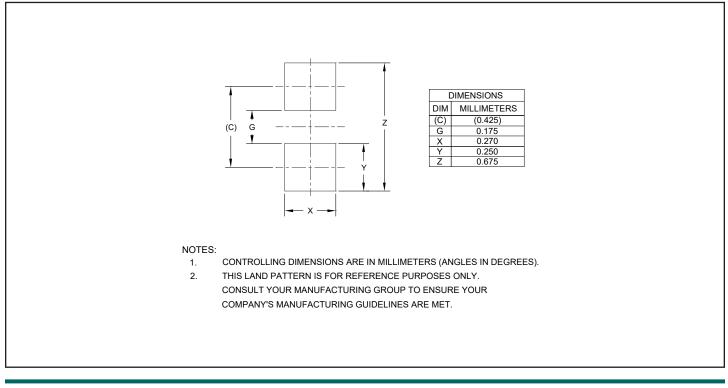
Table 1 - Assembly Guidelines

Assembly Parameter	Recommendation				
Solder Stencil Design	Laser Cut, Electro-Polished				
Aperture Shape	Rectangular with Rounded Corners				
Solder Stencil Thickness	0.075mm (0.003″) or 0.100mm (0.004″)				
Solder Paste Type	Type 4 Size Sphere or Smaller				
Solder Reflow Profile	Per JEDEC J-STD-020				
PCB Solder Pad Design	Solder Mask Defined or Non Solder Mask Defined				
PCB Pad Finish	OSP or NiAu				

Outline Drawing - SLP0603P2X3F



Land Pattern - SLP0603P2X3F

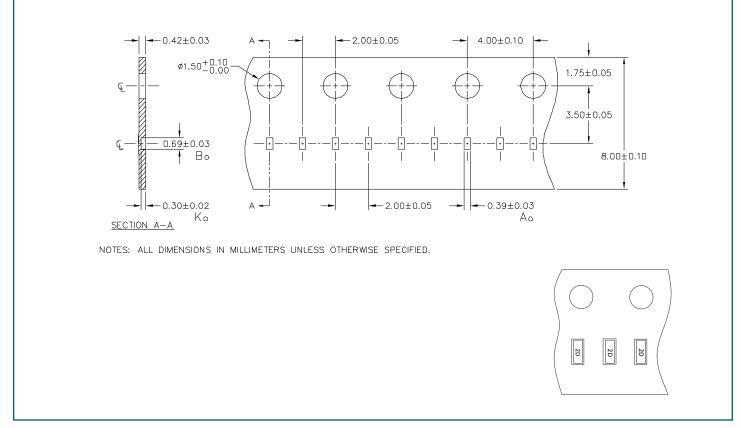


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Marking Code

2D

Tape and Reel Specification



Ordering Information

Part Number	Qty per Reel	Reel Size
RClamp3521ZATFT	15,000	7″
RClamp3521ZATNT	10,000	7″



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